

PMPB09R5VPX-VB Datasheet

P-Channel 30 V (D-S) MOSFET

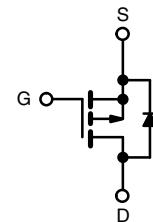
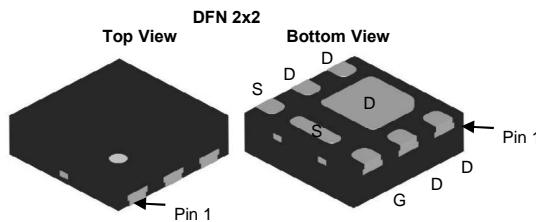
PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
- 30	0.022 at $V_{GS} = - 4.5$ V	-10 ^a	18 nC
	0.030 at $V_{GS} = - 2.5$ V	-9 ^a	

FEATURES

- Trench Power MOSFET
- Thermally Enhanced DFN2X2 Package
 - Small Footprint Area
 - Low On-Resistance



RoHS
COMPLIANT
HALOGEN
FREE



P-Channel MOSFET

APPLICATIONS

- Load Switch, PA Switch, and Battery Switch for Portable Devices

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	- 30	V	
Gate-Source Voltage	V_{GS}	± 12		
Continuous Drain Current ($T_J = 150$ °C)	$T_C = 25$ °C	- 10 ^a	A	
	$T_C = 70$ °C	- 8 ^a		
	$T_A = 25$ °C	- 10 ^{b, c}		
	$T_A = 70$ °C	- 8 ^{b, c}		
Pulsed Drain Current ($t = 300$ µs)	I_{DM}	- 30		
Continuous Source-Drain Diode Current	$T_C = 25$ °C	- 10 ^a	W	
	$T_A = 25$ °C	- 2.5 ^{b, c}		
Maximum Power Dissipation	$T_C = 25$ °C	17		
	$T_C = 70$ °C	11		
	$T_A = 25$ °C	3.3 ^{b, c}		
	$T_A = 70$ °C	2.1 ^{b, c}		
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) ^{d, e}		250		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, f}	R_{thJA}	28	38	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	5.6	7.5	

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t = 5$ s.
- d. See solder profile The DFN2X2 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 80 °C/W.

SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = -250 \mu\text{A}$	- 30			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250 \mu\text{A}$		- 11		mV/°C
$V_{GS(\text{th})}$ Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$			2.7		
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = -250 \mu\text{A}$	- 0.4		- 1	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -12 \text{ V}$, $V_{GS} = 0 \text{ V}$			- 1	μA
		$V_{DS} = -12 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 55^\circ\text{C}$			- 10	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \leq -5 \text{ V}$, $V_{GS} = -4.5 \text{ V}$	- 10			A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = -4.5 \text{ V}$, $I_D = -5 \text{ A}$		0.022		Ω
		$V_{GS} = -2.5 \text{ V}$, $I_D = -4 \text{ A}$		0.030		
		$V_{GS} = -1.8 \text{ V}$, $I_D = -2.3 \text{ A}$		0.042		
		$V_{GS} = -1.5 \text{ V}$, $I_D = -1 \text{ A}$		0.050		
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10 \text{ V}$, $I_D = -6.7 \text{ A}$		30		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = -10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$		2000		pF
Output Capacitance	C_{oss}			430		
Reverse Transfer Capacitance	C_{rss}			370		
Total Gate Charge	Q_g	$V_{DS} = -6 \text{ V}$, $V_{GS} = -8 \text{ V}$, $I_D = -10 \text{ A}$		38	54	nC
Gate-Source Charge	Q_{gs}			23	33	
Gate-Drain Charge	Q_{gd}			3		
Gate Resistance	R_g		$f = 1 \text{ MHz}$	6.5		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -6 \text{ V}$, $R_L = 0.75 \Omega$ $I_D \approx -8 \text{ A}$, $V_{GEN} = -4.5 \text{ V}$, $R_g = 1 \Omega$		7		Ω
Rise Time	t_r			20	30	ns
Turn-Off Delay Time	$t_{d(\text{off})}$			40	60	
Fall Time	t_f			65	100	
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -6 \text{ V}$, $R_L = 0.75 \Omega$ $I_D \approx -8 \text{ A}$, $V_{GEN} = -8 \text{ V}$, $R_g = 1 \Omega$		40	60	ns
Rise Time	t_r			10	15	
Turn-Off Delay Time	$t_{d(\text{off})}$			12	20	
Fall Time	t_f			70	105	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25^\circ\text{C}$			- 10	A
Pulse Diode Forward Current	I_{SM}				- 15	
Body Diode Voltage	V_{SD}	$I_S = -8 \text{ A}$, $V_{GS} = 0 \text{ V}$		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -8 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $T_J = 25^\circ\text{C}$		40	60	ns
Body Diode Reverse Recovery Charge	Q_{rr}			20	30	nC
Reverse Recovery Fall Time	t_a			14		ns
Reverse Recovery Rise Time	t_b			26		

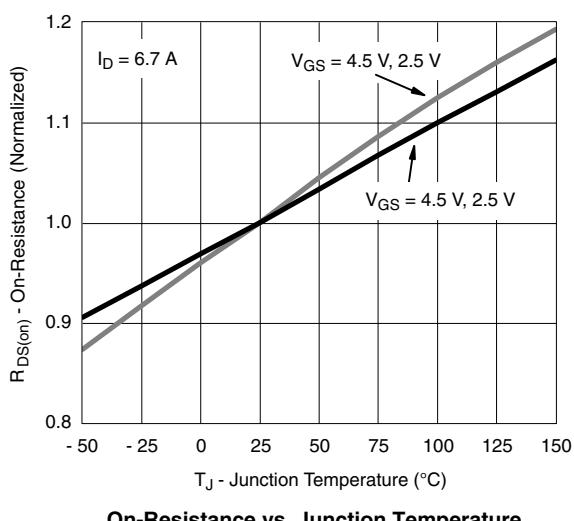
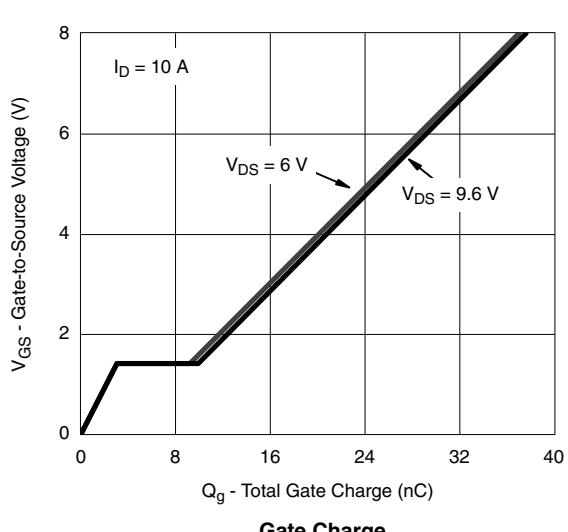
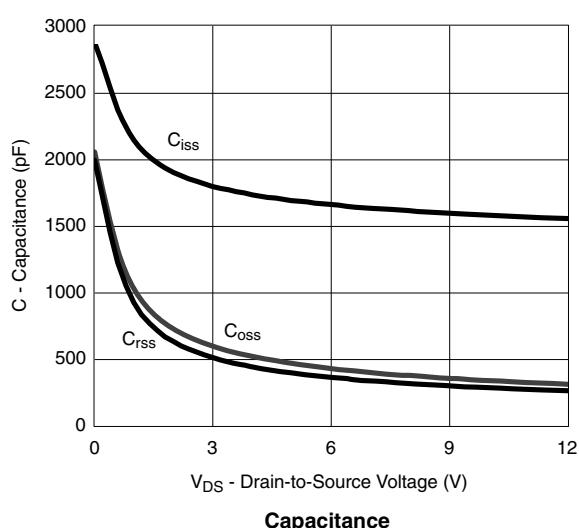
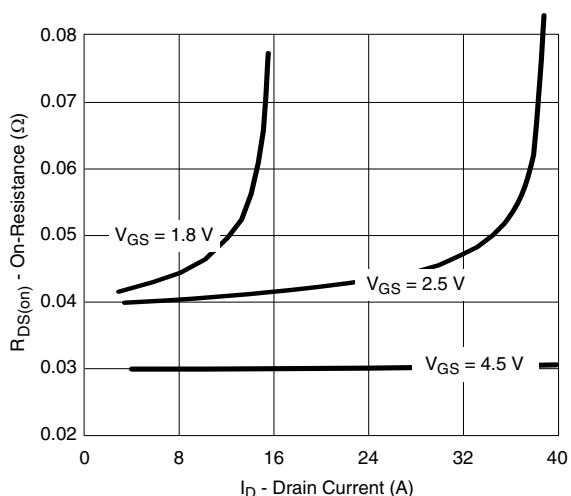
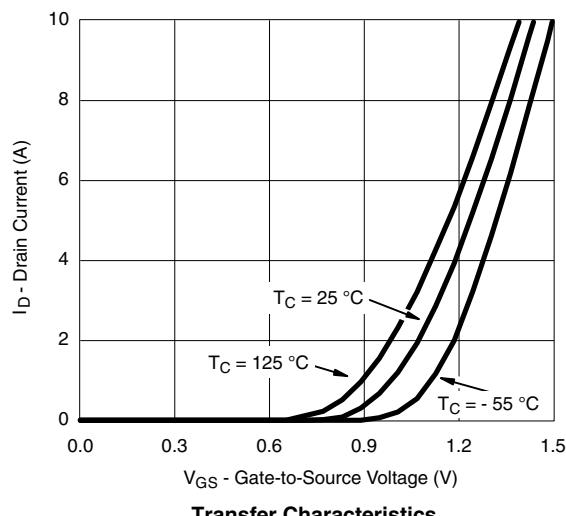
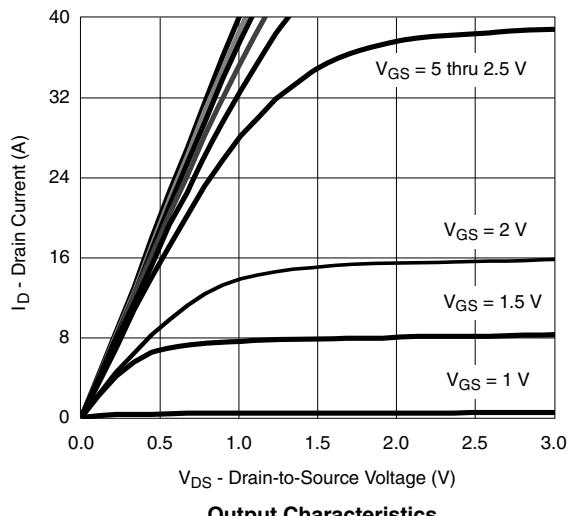
Notes:

a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

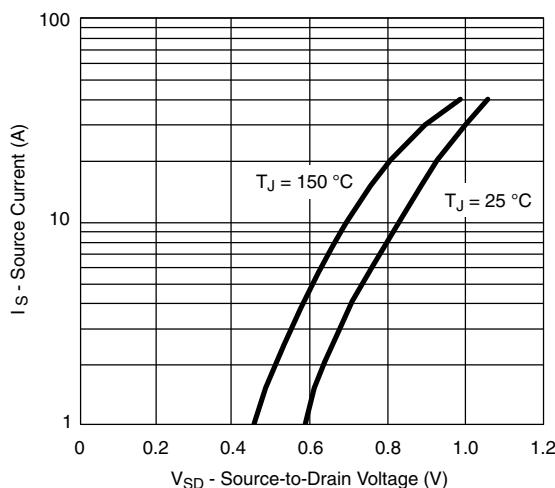
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

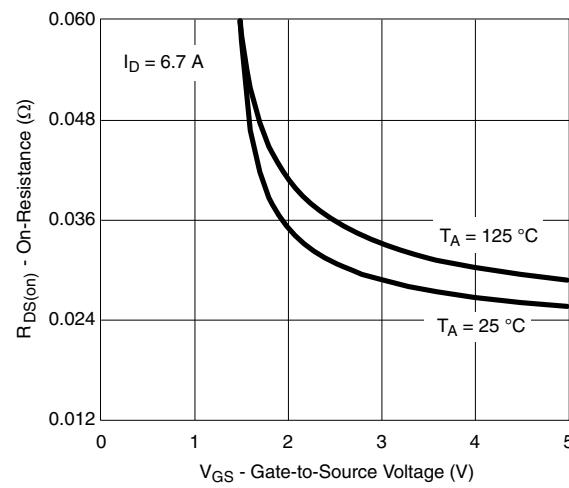
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



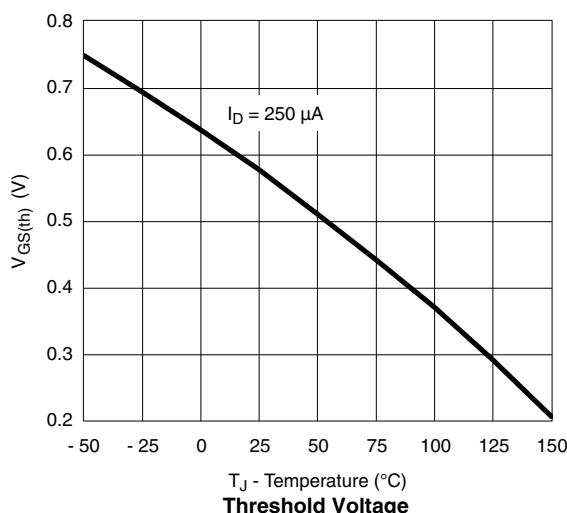
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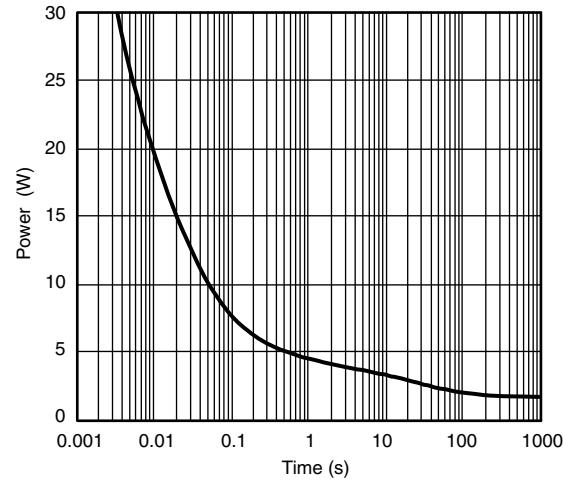
Source-Drain Diode Forward Voltage



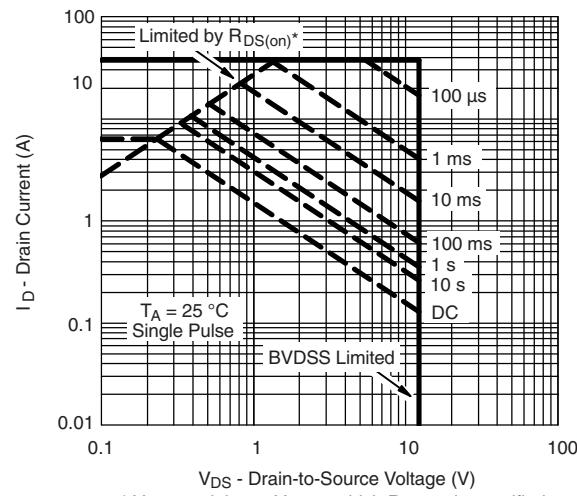
On-Resistance vs. Gate-to-Source Voltage



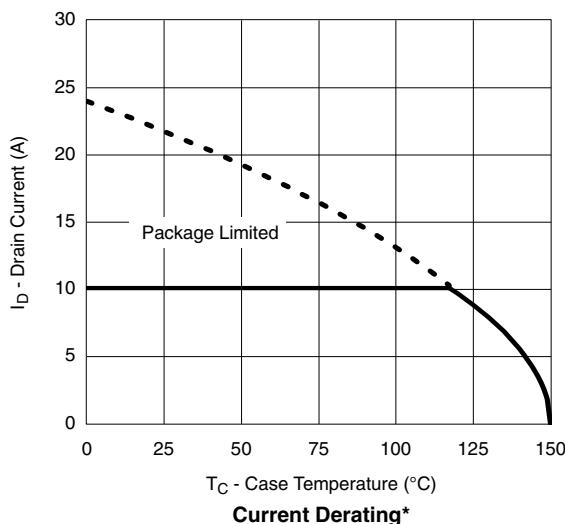
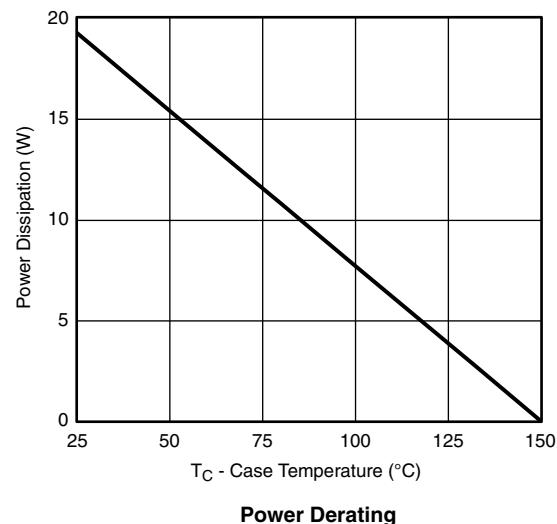
Threshold Voltage



Single Pulse Power, Junction-to-Ambient

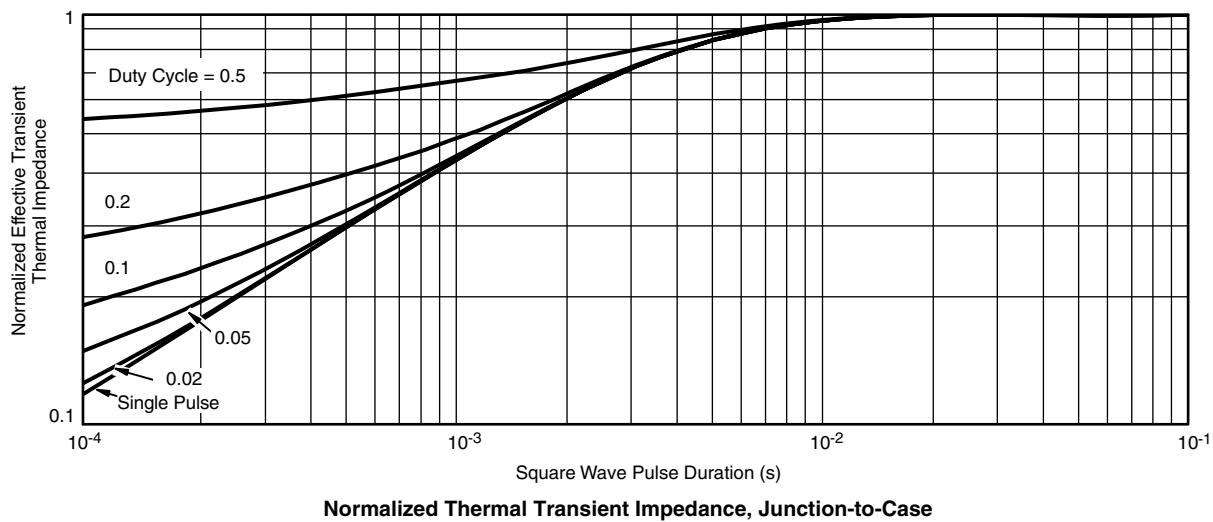
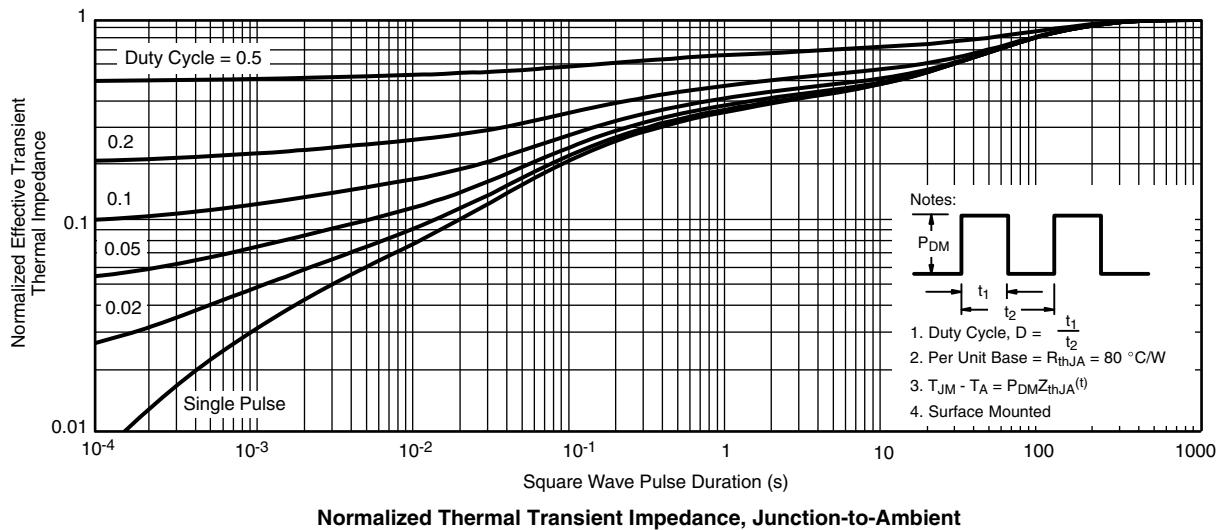


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(\text{on})}$ is specified
Safe Operating Area, Junction-to-Ambient

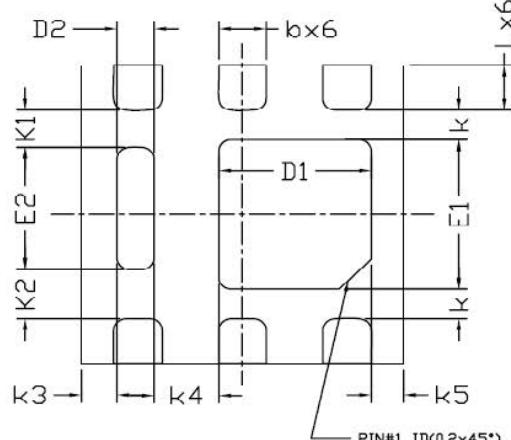
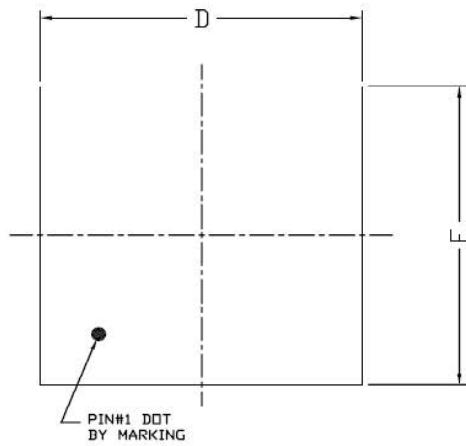
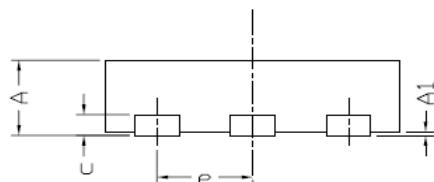
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)
**Current Derating*****Power Derating**

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

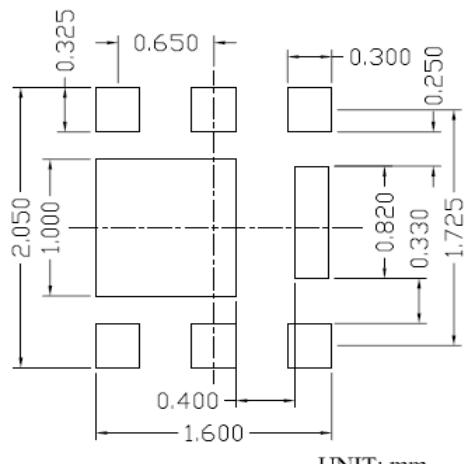
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



DFN2x2 _6L_EP1_S PACKAGE OUTLINE

BOTTOM VIEW

RECOMMENDED LAND PATTERN



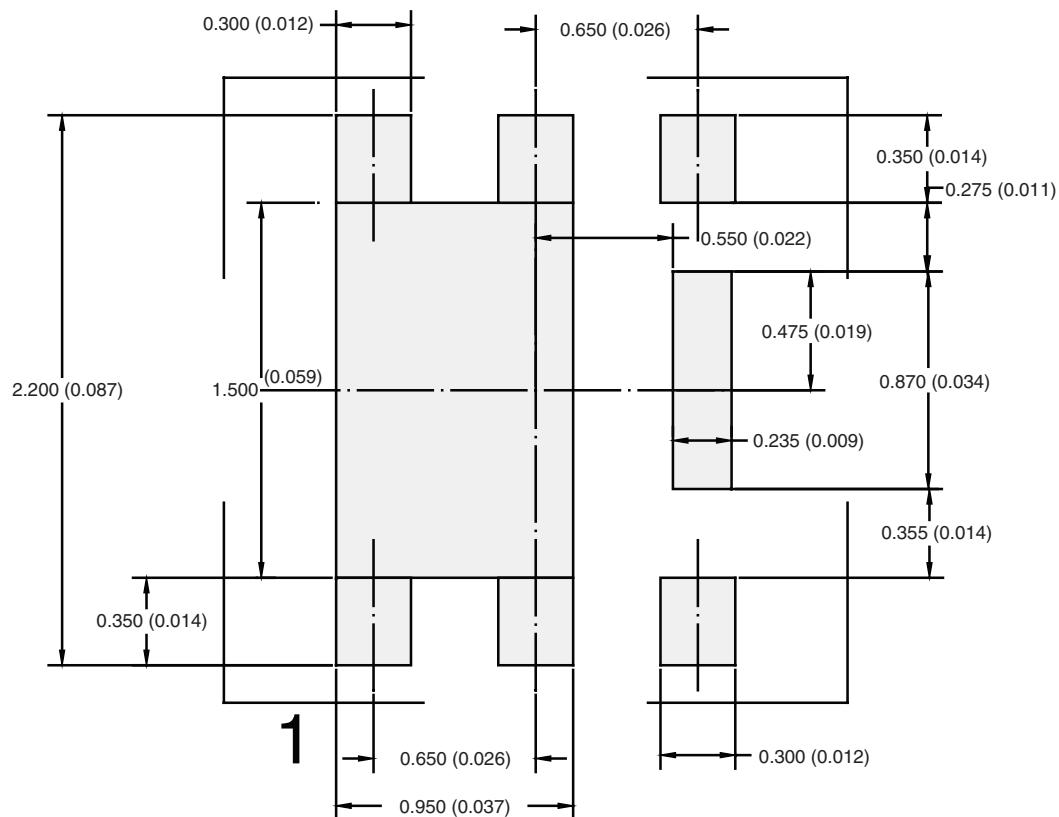
UNIT: mm

NOTE

1. CONTROLLING DIMENSION IS MILLIMETER.
- CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
A1	0.00	—	0.05	0.000	—	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.152 REF			0.006 REF		
D	1.90	2.00	2.10	0.075	0.079	0.083
D1	0.85	0.95	1.05	0.033	0.037	0.041
D2	0.13	0.23	0.33	0.005	0.009	0.013
E	1.90	2.00	2.10	0.075	0.079	0.083
E1	0.90	1.00	1.10	0.035	0.039	0.043
E2	0.72	0.82	0.92	0.028	0.032	0.036
e	0.65 BSC			0.026 BSC		
K	0.20 BSC			0.008 BSC		
K1	0.25 BSC			0.010 BSC		
K2	0.33 BSC			0.013 BSC		
K3	0.22 BSC			0.009 BSC		
K4	0.40 BSC			0.016 BSC		
K5	0.20 BSC			0.008 BSC		
L	0.25	0.30	0.35	0.010	0.012	0.014

RECOMMENDED PAD LAYOUT FOR DFN2X2



Dimensions in mm/(Inches)

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